

Count	RefDes	Value	Description	Size	Manufacture Part #
2	C1,C7	1500PF	CAP_SM-CE,1500PF,50V,10%,0402_X7R_PB-FR	C0402	STD
2	C2,C8	2200PF	CAP_SM-CE,2200PF,50V,10%,0402_X7R	C0402	STD
2	C3,C10	220PF	CAP_SM-CE,220PF,50V,10%,0402_X7R_PB-FR	C0402	STD
3	C4,C5,C11	1uF	CAP_SM-CE,1UF,25V,10%,0603_X7R_PB-FR	C0603	STD
6	C6,C9,C31,C48,C23,C34	0.1UF	CAP_SM-CE,0.1UF,16V,10%,0402_X7R_0.5MM	C0402	STD
4	C12,C13,C30,C47	1000PF	CAP_SM-CE,1000PF,50V,10%,0402_X7R_PB-FR	C0402	STD
4	C14,C15,C16,C17	47UF	PCAP_SM-TA,47UF,16V,20%,2816_LOW_ESR	C7343	16TQC47M
2	C18,C39	0.1UF	CAP_SM-CE,0.1UF,25V,20%,0603_X7R_PB-FR	C0603	STD
4	C19,C20,C40,C41	47UF	CAP_SM-CE,47UF,16V,20%,1210_X5R	C1210	GRM32ER61C476ME15L
2	C21,C42	22UF	CAP_SM-CE,22UF,16V,10%,1206_X5R_PB-FR	C1206	GRM31CR61C226KE15
2	C22,C43	3300PF	CAP_SM-CE,3300PF,50V,10%,0402_X7R	C0402	STD
8	C24,C25,C26,C27,C35, C36,C37,C38	470UF	PCAP_SM-TA,470UF,4V,20%,2816_GSM_PREFRD	C7343	4TPF470ML
4	C28,C29,C44,C45	100UF	CAP_SM-CE,100UF,6.3V,20%,1210_X5R_PB-FR	C1210	GRM32ER60J107ME20K
2	C32,C49	2.2UF	CAP_SM-CE,2.2UF,16V,10%,0603_X5R	C0603	STD
2	C33,C46	3300PF	CAP_SM-CE,3300PF,50V,10%,0603_PB-FR	C0603	STD
2	C50,C51	330PF	CAP_SM-CE,330PF,50V,5%,0402_NPO	C0402	STD
1	C100	470UF	PCAP_SM-AL,470UF,16V,20%,8MMD_10.8MML	C3333	16SVPE470M
2	J1,J2		CON1X3_F-ST,NONE,AMPHENOL_A-1JA,COAX	CON-3	A-1JA
2	L1,L2	150nH	IND_SM-150NH,15%,41A,FERR_PB-FR	L3630	PA2607NL-151
3	P1,P2,P3		PWR4_M-ST,MOLEX_15-24-4345,0.200C	CON-4	ED120/4DS
3	P4,P8,P9		HDR1X2_M-ST,NONE,TSW-102-08-G-S	CON-2	TSW-102-08-G-S
1	P12		HDR2X5_M-ST,SHDR_PB-FR,MOLEX_70246-1002	CON-10	AWHW10G-0202-T-R
0	R1,R3,R5,R7,R18,R20, R22,R23,R32,R33	0	RES_SM-TF,0,0.063W,5%,0402_PBFREE	R0402	STD
2	R2,R13	511	RES_SM-TF,511,0.063W,1%,0402	R0402	STD
2	R4,R14	10K	RES_SM-TF,10K,0.063W,0.1%,0402_25PPM_PB-FR	R0402	STD
2	R6,R15	4.99K	RES_SM-TKF,4.99K,0.063W,1%,0402	R0402	STD
2	R8,R19	10	RES_SM-TF,10,0.063W,1%,0402	R0402	STD
2	R9,R16	15K	RES_SM-TF,15K,0.063W,0.1%,0402_25PPM_PB-FR	R0402	STD
0	R10,R17	100K	RES_SM-TF,100K,0.063W,1%,0402	R0402	STD
2	R11,R21	0	RES_SM-TF,0,0.063W,5%,0402	R0402	STD
1	R12	40.2K	RES_SM-TF,40.2K,0.063W,1%,0402_PB-FR	R0402	STD

1	R24	38.3K	RES_SM-TF,38.3K,0.063W,1%,0402	R0402	STD
1	R25	53.6K	RES_SM-TF,53.6K,0.063W,1%,0402	R0402	STD
2	R26,R30	1	RES_SM-TF,1,0.063W,1%,0402_PB-FR	R0402	STD
2	R27,R29	49.9	RES_SM-TF,49.9,0.063W,1%,0402	R0402	STD
2	R28,R31	1	RES_SM-TF,1,0.100W,5%,0603_PB-FR	R0603	STD
0	R100,R101,R102	0.001	RES_SM-MF,0.001,2.00W,1%,2512	R2512	STD
1	U1		TPS40428_QFN40-DUAL-OUT_2-PHS_PMB_BUCK_CNTRL	QFN40	TPS40428
2	U2,U3		CSD95378BQ5M_SON13,SYN_BUCK_NEXFET_PWR_STAGE	DFN13	CSD95378BQ5M

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